



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Cobbley et al.

Serial No.: 10/721,110

Filed: November 24, 2003

For: METHOD FOR IN-LINE TESTING OF FLIP-CHIP SEMICONDUCTOR

or reir-chip semicond

ASSEMBLIES

Confirmation No.: 6106

Examiner: R. Kobert

Group Art Unit: 2829

Attorney Docket No.: 2269-3437.9US

(97-0514.09/US)

Notice of Allowance Mailed:

June 28, 2005

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 8, 200

Date

Leta M. Howard

Name (Type/Print)

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.